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March 2015

### FQT13N06L

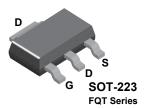
# N-Channel QFET $^{\mathbb{R}}$ MOSFET 60 V, 2.8 A, 110 m $\Omega$

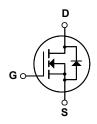
#### **General Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor®'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

#### **Features**

- 2.8 A, 60 V,  $R_{DS(on)}$  = 110 m $\Omega$  (Max.) @V  $_{GS}$  = 10 V,  $I_D$  = 1.4 A
- Low Gate Charge (Typ. 4.8 nC)
- Low Crss (Typ. 17 pF)
- · 100% Avalanche Tested





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQT13N06L	Unit	
$V_{DSS}$	Drain-Source Voltage		60	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C	)	2.8	А	
	- Continuous (T <sub>C</sub> = 70°C)		2.24	Α	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	11.2	А	
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	85	mJ	
I <sub>AR</sub>	Avalanche Current (Note 1)		2.8	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		0.21	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		7.0	V/ns	
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C)		2.1	W	
	- Derate above 25°C		0.017	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Rang	е	-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		60	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended(PCB mount).

Symbol	Parameter	Test Conditions	1	Min	Тур	Max	Unit
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced	to 25°C		0.05	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V				1	μΑ
		V <sub>DS</sub> = 48 V, T <sub>C</sub> = 125°C				10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V				-100	nA
On Cha	aracteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1.0		2.5	V
R <sub>DS(on)</sub>	Static Drain-Source	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1.4 A			0.088	0.11	
DO(OII)	On-Resistance	V <sub>GS</sub> = 5 V, I <sub>D</sub> = 1.4 A			0.110	0.14	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 1.4 A	(Note 4)		4.1		S
C <sub>iss</sub>	ic Characteristics Input Capacitance	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,			270	350	pF
Coss	Output Capacitance	f = 1.0 MHz			95	125	pF
C <sub>rss</sub>	Reverse Transfer Capacitance				17	23	pF
Switchi	ing Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	V -20 V I -6 9 A			8	25	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 6.8 \text{ A},$ $R_{G} = 25 \Omega$			90	190	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	11G - 25 52			20	50	ns
t <sub>f</sub>	Turn-Off Fall Time		(Note 4, 5)		40	90	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 48 V, I <sub>D</sub> = 13.6 A,			4.8	6.4	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 5 V			1.6	-	nC
	Gate-Drain Charge		(Note 4, 5)		2.7		nC
$Q_{gd}$		1					
	Source Diode Characteristics a	nd Maximum Ratings	s				
Drain-S	Source Diode Characteristics at Maximum Continuous Drain-Source Dio		<b>S</b>			2.8	Α
Drain-S		ode Forward Current	S			2.8 11.2	A
Drain-S	Maximum Continuous Drain-Source Dic	ode Forward Current Forward Current	S				
Drain-S	Maximum Continuous Drain-Source Dio Maximum Pulsed Drain-Source Diode F	ode Forward Current	5		   45	11.2	Α

- Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 12.6 mH,  $I_{AS}$  = 2.8 A,  $V_{DD}$  = 25 V,  $R_{G}$  = 25  $\Omega$ , starting  $T_{J}$  = 25°C. 3.  $I_{SD}$  ≤ 13.6 A, di/dt ≤ 300  $A/\mu s$ ,  $V_{DD}$  ≤ B $V_{DSS}$ , starting  $T_{J}$  = 25°C. 4. Pulse test : pulse width ≤ 300  $\mu s$ , Duty cycle ≤ 2%. 5. Essentially independent of operating temperature.

### **Typical Characteristics**

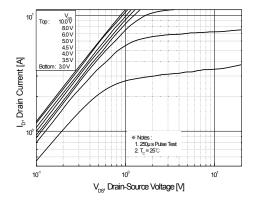


Figure 1. On-Region Characteristics

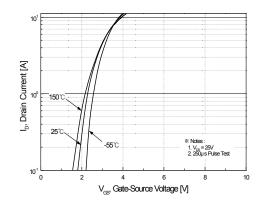


Figure 2. Transfer Characteristics

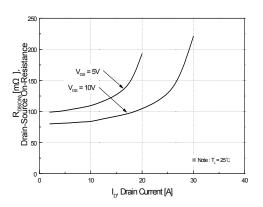


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

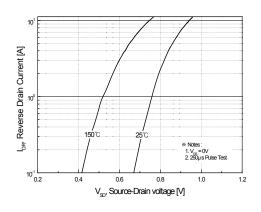


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

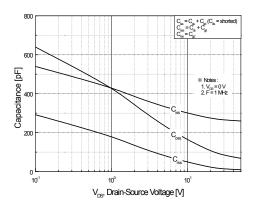


Figure 5. Capacitance Characteristics

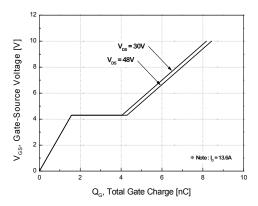
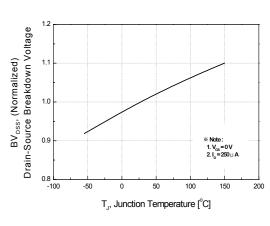


Figure 6. Gate Charge Characteristics

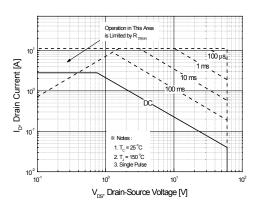


Typical Characteristics (Continued)

25 0220 (bazi guardian Junction Temperature (°C)

Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



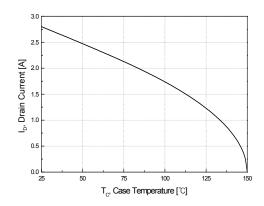


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

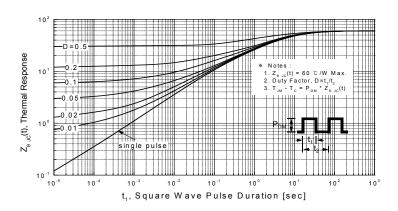


Figure 11. Transient Thermal Response Curve



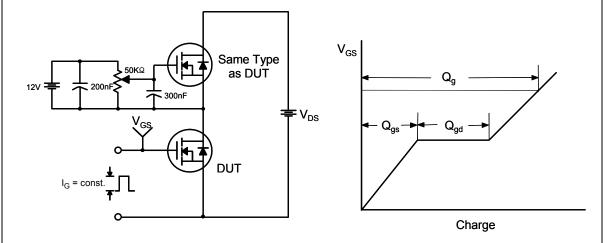


Figure 13. Resistive Switching Test Circuit & Waveforms

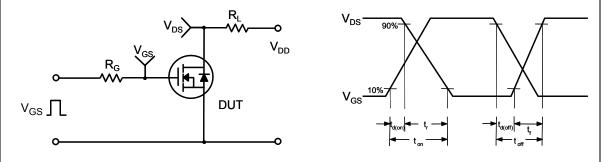
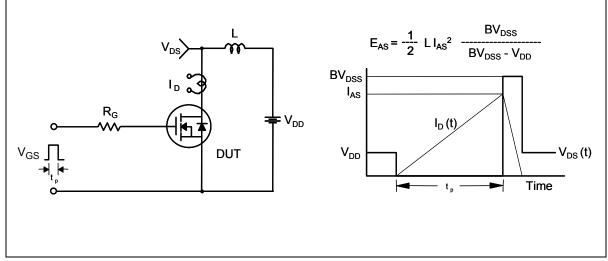
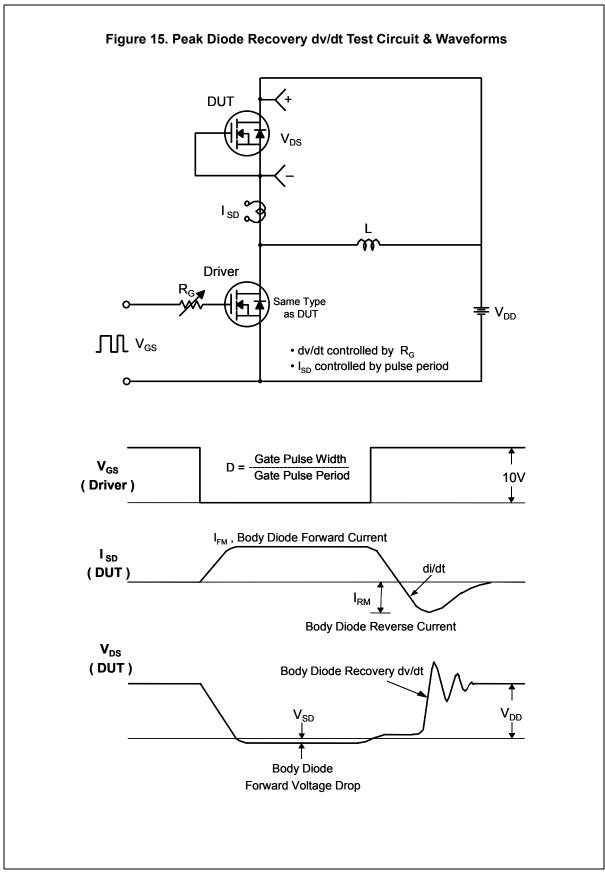
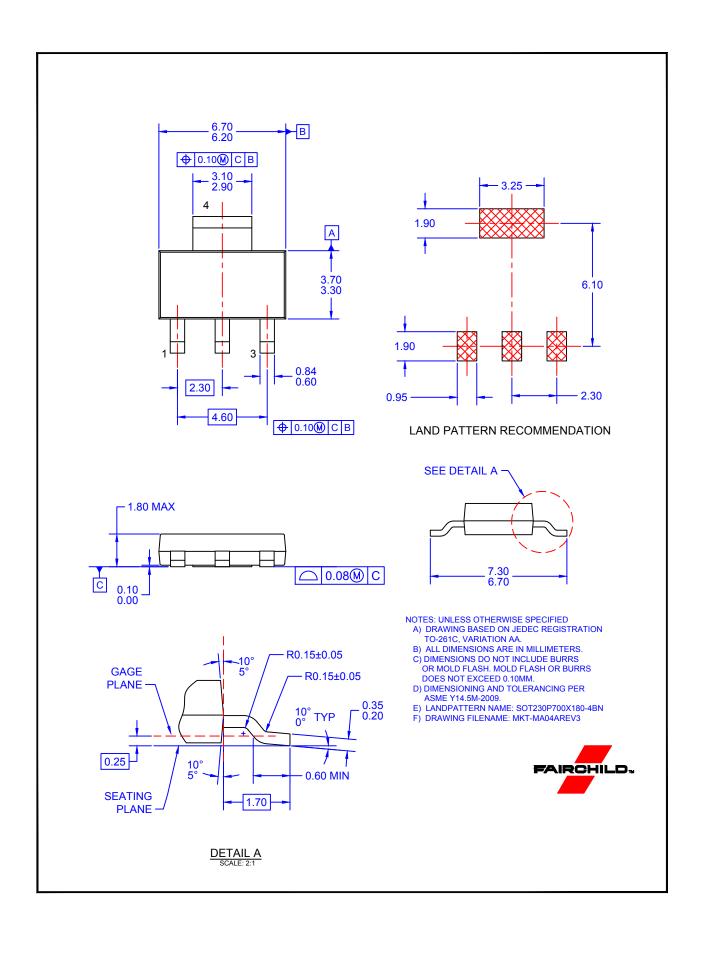


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms







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